Vishay Siliconix

COMPLIANT

HALOGEN

FREE

P-Channel 80 V (D-S) MOSFET

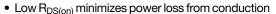


PRODUCT SUMMARY					
V _{DS} (V)	-80				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.0058				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5 \text{ V}$	0.0081				
Q _g typ. (nC)	145				
I _D (A)	-150				
Configuration	Single				

FEATURES

- TrenchFET® power MOSFET
- · Package with low thermal resistance

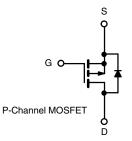




- · Compatible with logic-level gate driving
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Battery protection
- Motor drive control
- · Load switch



ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free and halogen-free	SUP60061EL-GE3			
4 DAGA 11 DA DAGA /T. 05 00				

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-source voltage		V _{DS}	-80	V	
Gate-source voltage		V _{GS}	V _{GS} ± 20		
Continuous drain current ^d	T _C = 25 °C	I _D	-150 ^d		
(T _J = 175 °C)	T _C = 70 °C		-150 ^d		
Pulsed drain current (100 μs)		I _{DM}	-250	A	
Avalanche current	L = 0.1 mH		-75]	
Single pulse avalanche energy ^a	L = 0.1 IIII	E _{AS}	281	mJ	
Power dissipation	T _C = 25 °C °	Pn	375	- w	
	T _C = 125 °C b	TD FD	125		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount ^b	R_{thJA}	40	°C/W	
Junction-to-case		R_{thJC}	0.4	C/VV	

Notes

- a. Duty cycle ≤ 1 %
- b. When mounted on 1" square PCB (FR4 material)
- c. See SOA curve for voltage derating
- d. Limited by package



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -10 \text{ mA}$	-80	-	-	V	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1.5	-	-2.5		
Gate-body leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
		V _{DS} = -80 V, V _{GS} = 0 V	-	-	-10	-50 μA	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -64 V, V _{GS} = 0 V, T _J = 125 °C	-	-	-50		
		V _{DS} = -64 V, V _{GS} = 0 V, T _J = 175 °C	-	-	-250		
On-state drain current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	-30	-	-	Α	
Drain accuracy on atota vaciations 3	В	V _{GS} = -10 V, I _D = -20 A	-	0.0048	0.0058		
Drain-source on-state resistance a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -15 \text{ A}$	-	0.0065	0.0081	Ω	
Forward transconductance ^a	9 _{fs}	V _{DS} = -15 V, I _D = -15 A	-	80	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	9600	-	pF	
Output capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -40 \text{ V}, f = 1 \text{ MHz}$	-	3300	-		
Reverse transfer capacitance	C _{rss}		-	110	=		
Total gate charge ^c	Qg		-	145	218		
Gate-source charge ^c	Q _{gs}	$V_{DS} = -40 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -110 \text{ A}$	-	34	-	nC	
Gate-drain charge ^c	Q _{gd}		-	16	-		
Gate resistance	Rg	f = 1 MHz	0.46	2.3	4.6	Ω	
Turn-on delay time ^c	t _{d(on)}		-	25	35		
Rise time ^c	t _r	$V_{DD} = -40 \text{ V}, R_1 = 0.71 \Omega$	-	20	30		
Turn-off delay time ^c	t _{d(off)}	$I_D \cong -20 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	-	90	140	ns	
Fall time ^c	t _f		-	20	30		
Drain-Source Body Diode Characte	ristics (T _C = 25	5 °C b)					
Continuous current	Is		-	-	-150	۸	
Pulsed current	I _{SM}		-	-	-250	Α	
Forward voltage ^a	V _{SD}	I _F = -10 A, V _{GS} = 0 V	-	-0.8	-1.5	V	
Reverse recovery time	t _{rr}		-	90	135	ns	
Peak reverse recovery charge	I _{RM(REC)}	I _F = -20 A, dl/dt = 100 A/μs	-	-2.8	-4.2	Α	
Reverse recovery charge	Q _{rr}		-	145	218	nC	

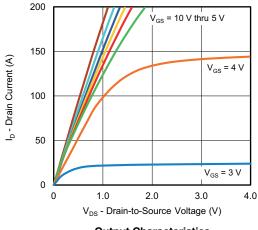
Notes

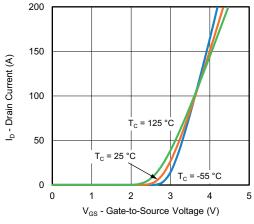
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



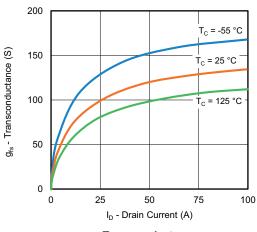
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

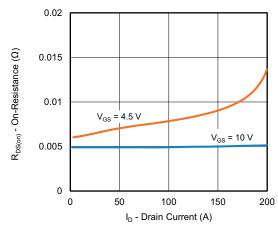




Output Characteristics

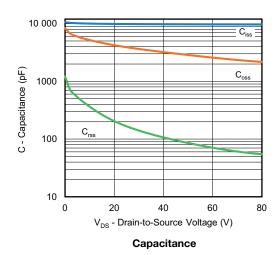


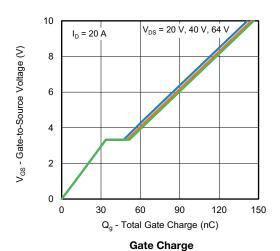




Transconductance

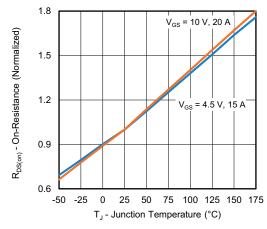
On-Resistance vs. Drain Current



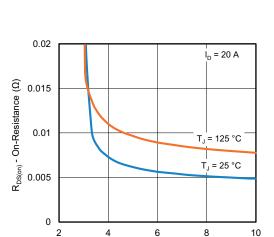




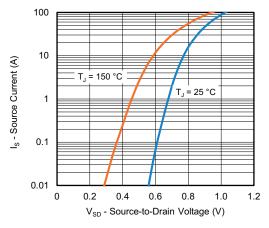
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



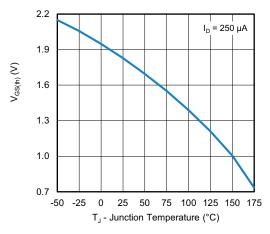
On-Resistance vs. Junction Temperature



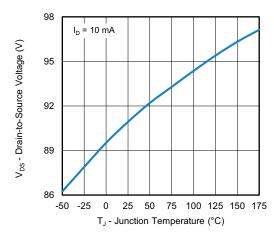
 $\label{eq:VGS} V_{GS} \text{ - Gate-to-Source Voltage (V)}$ On-Resistance vs. Gate-to-Source Voltage



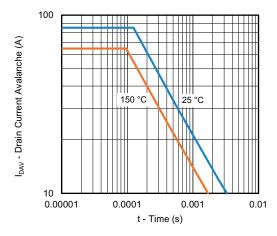
Source Drain Diode Forward Voltage



Threshold Voltage



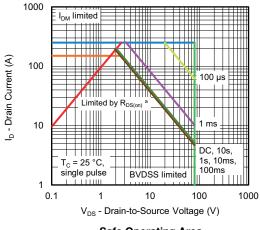
Drain Source Breakdown vs. Junction Temperature



Avalanche Current vs. Time



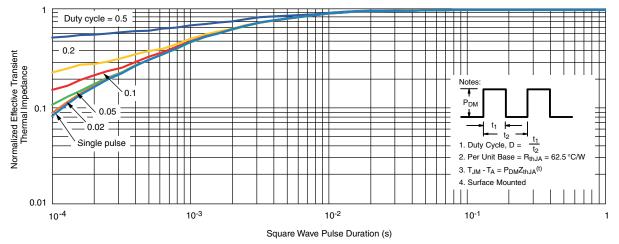
THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?63020.





TO-220AB



	D2

	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

Note

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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